

L Number	Hits	Search Text	DB	Time stamp
1	147	((thourgh hole thoughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carrier))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 19:40
2	203	((through hole throughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carrier))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 19:41
3	56	((through hole throughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carrier)))) not ((thourgh hole thoughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carrier))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 19:41

L Number	Hits	Search Text	DB	Time stamp
1	517583	(silicon silicon semiconductor bulk gaas) with (substrate carruer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 10:28
2	3958	(taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 10:28
3	496	(thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 10:29
4	145	(thourgh hole thoughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/16 10:30